

Abstract of the Disclosure

A semiconductor device has a plurality of laminated semiconductor elements 2, and highly water-absorbing resin films 3 formed between
5 the semiconductor elements. Here, the highly water-absorbing resin films 3 preferably contain water or a low-boiling-point organic solvent. Alternatively, the highly water-absorbing resin films may contain, or may be allowed to contain after packaging, an organic solvent having a boiling point equal to or higher than the reflow temperature of solder.